tilogo2c

**SN74AC244**

|  |  |  |  |  |  |
| --- | --- | --- | --- | --- | --- |
| SHEREL.95.ACL.11115 | | **SN74AC244 ESD** | |  |  |
| **Device:** | SN74AC244 | **Die Rev:** | A |  |  |
| **Technology:** | CMOS |  |  |  |  |

|  |  |  |  |
| --- | --- | --- | --- |
| **Test Type** | **Voltage** | **Qty** | **Fails** |
| ESD - HBM | 500 V | 3 | 0 |
|  | 1000 V | 3 | 0 |
|  | 1500 V | 3 | 0 |
|  | 2000 V | 3 | 0 |
|  |  |  |  |
| ESD - MM | 50 V | 3 | 0 |
|  | 100 V | 3 | 0 |
|  | 150 V | 3 | 0 |
|  | 200 V | 3 | 0 |
|  |  |  |  |
| ESD - CDM | 250 V | 3 | 0 |
|  | 500 V | 3 | 0 |
|  | 750 V | 3 | 0 |
|  | 1000 V | 3 | 0 |

**Wafer Fabrication Process Family Reliability Testing Data**

The following data is for testing completed on various part number devices with die fabricated using the same die fabrication process as the subject part number device. This data is not specific to the subject device.

Top of Form

Bottom of Fo

Top of Form

Bottom of Form

|  |  |  |  |
| --- | --- | --- | --- |
| **Test** | **Conditions** | **Quantity Tested** | **Failures** |
| AUTOCLAVE | 15 psig, 121 Degrees C,96 Hours | 1652 | 0  Top of Form |
| HAST | 130 Degrees C / 85 % RH with bias,96 Hours | 1155 | 0  Top of Form |
| LIFE TEST | 125C,1000 Hours | 630 | 0  Top of Form |
| TEMP CYCLE | -65 / +150 Degrees C,1000 Cycles | 1155 | 0  Top of Form |
| THERMAL SHOCK | -65 / +150 Degrees C,1000 Cycles | 231 | 0  Bottom of Form  Bottom of Form  Bottom of Form  Bottom of Form |

**Use Disclaimer:**

Plastic encapsulated TI semiconductor devices are not designed and are not warranted to be suitable for use in some military applications and/or military environments. Use of plastic encapsulated TI semiconductor devices in military applications and/or military environments, in lieu of hermetically sealed ceramic devices, is understood to be fully at the risk of the buyer.

**Quality and Reliability Data Disclaimer:**

TI assumes no liability for applications assistance or customer product design. Customers are responsible for their products and applications using TI components. To minimize the risks associated with customer products and applications, customer should provide adequate design and operating safeguards.

Quality and reliability data provided by Texas Instruments is intended to be an estimate of product performance based upon history only. It does not imply that any performance levels reflected in such data can be met if the product is operated outside the conditions expressly stated in the latest published data sheet for a device. Device attributes listed in qualification reports may not reflect materials or processes currently being used in the construction of the devices.

Reliability data shows characteristic failure mechanisms of the specific environmental stress as documented in the industry standards for each stress condition.

TI warrants its devices as per datasheet limits.  Any usage outside of these limits is the sole responsibility of the consumer and voids all warranties and responsibilities from TI.

**THIS INFORMATION SHOULD NOT BE USED TO ASSIST IN THE PRACTICE OF “UPRATING” OR “UPSCREENING” DEVICES FOR USE BEYOND THEIR RATED LIMITS.**